

Filename: PMP5211A_bom.xls

Date: 10/29/2009

PMP5211A BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	.1uF	Capacitor, Ceramic, X7R, 10%	603	{std}	
1	C2	omit	Capacitor, Ceramic, X7R, 10%	603	{std}	
1	C3	10uF	Capacitor, Aluminum, 10-uF, 25-V, 20%	0.177 x 0.177	EEV-FK1E100R	Panasonic
2	C4, C9	1000pF	Capacitor, Ceramic, 1000-pF, 50-V, XR7	805	{std}	{std}
1	C5	100uF	Capacitor, Aluminum, 6.3V, ±20%, 240mArms, 360mohms	0.260 x 0.276 in	EEVFK0J101P	Panasonic
1	C6	220uF	Capacitor, Aluminum, 6.3V, ±20%		EEVFK0J221P	Panasonic
1	C7	omit	Capacitor, Ceramic, 50-V, NPO	603	{std}	{std}
1	C8	0.68uF	Capacitor, Ceramic, X7R, 0.68-uF, 16V	603	{std}	
1	D1	Red	Diode, LED, Red, 1.7-V, 40-mcd, SM	1210	SML-LX2832SRC-	Lumex
1	D2	30BQ015	Diode, Schottky, 3A, 15V		30BQ015	IR
1	D5	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	BAT54	Vishay-Liteon
1	J1		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
1	J2		Terminal Block, 4-pin, 6-A, 3.5mm	0.55 x 0.25"	ED1516	OST
1	L1	10uHy	Inductor, SMT	0.264 sq inch	DR125-100-R	Cooper/Coiltronics
1	Q1	CSD25401Q3	MOSFET, P-ch, 20V, 8.8-milliOhms	SON 3x3	CSD25401Q3	Texas Instruments
1	Q2	MMBT3906	Bipolar, PNP, 40-V, 200-mA, .22-W	SOT23	MMBT3906-7	on semiconductor
1	Q3	MMBT3904	Bipolar, NPN, 40-V, 200-mA, 250-mW	SOT23	MMBT3904	Fairchild
1	R1	100K	Resistor, Chip, 100k-Ohms, 1/16-W, 1%	603	Std	Std
1	R11	330	Resistor, Chip, 330-Ohms, 1/16-W, 1%	603	Std	Std
1	R12	499	Resistor, Chip, 499-Ohms, 1/16-W, 1%	603	Std	Std
1	R13	604	Resistor, Chip, 604-Ohms, 1/16-W, 1%	603	Std	Std
1	R2	2K	Resistor, Chip, 2k-Ohms, 1/16-W, 1%	603	Std	Std
1	R23	14k	Resistor, Chip, userk-Ohms, 1/16-W, 1%	603	Std	Std
1	R3	0.05	Resistor, Chip, 1/8W, 5%	1206	Std	Std
1	R4	14.7K	Resistor, Chip, 14.7k-Ohms, 1/16-W, 1%	603	Std	Std
1	R5	31.6K	Resistor, Chip, 31.6k-Ohms, 1/16-W, 1%	603	Std	Std
1	R6	475k	Resistor, Chip, 475k-Ohms, 1/16-W, 1%	603	Std	Std
1	R18	open		603	Std	Std
1	R9	1K	Resistor, Chip, 1k-Ohms, 1/16-W, 1%	603	Std	Std
1	U1	BQ2000PW	IC, Fast Charge, Mult-chemistry	TSSOP-8	BQ2000PW	TI
1	--		PCB, 0 In x 0 In x 0 In		HPA250	Any

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.
 5. See schematic for jumpers needed and external 10k NTC thermistor.

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